IPC ASSOCIATION ELECTRONICS	Material C © Copyright 2 international a	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Materia	ials and Mfg Information			
upplier	Information														
Company name* Company				any unique ID			Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Na	nme	Title - Contac	Title - Contact			Phone - Contact*					Email - Contact*				
Product-E	nv-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Repres	Title - Representative			Phone - Representative*					Email - Representative*				
Product-E	nv-Stewards	Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr		Item Number Mfr Item Name				Effective Date Version Manufacturing		Site	Weight*		UOM	Unit Type		
		LC87F7932BUWC-3H 8-bit M		8-bit Microcontroll	-bit Microcontroller		2023-06-08	023-06-08 PHM		PHM	400.0		00.0	mg	Each
Ianufac	turing Proccess Info	ormation													·
7	Terminal Plating / Grid Ar	Terminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperat		ure Max Time	at Peak T	Temperatu	ire Num	ber of Reflow Cyo	eles			
contains Bi		CU Alloy 3			<b>260</b> C		30		second	ls <b>3</b>					
omments															
<u> </u>	ON: MSL 3 Rated item re	equires Bake and	Dry Pack (after	electrical test)											
or more ir	nformation regarding ma	aterial composition	n please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.16	mg	Supplier	Silicon (Si)	7440-21-3		4.1342	mg
			Supplier	Polyimide	Proprietary Data		0.0258	mg
Die Attach	1.03	mg	Supplier	Silver (Ag)	7440-22-4		0.7008	mg
			Supplier	Epoxy resins	129915-35-1		0.2979	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0225	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0089	mg
Lead Frame	237.42	mg	Supplier	Silver (Ag)	7440-22-4		1.2821	mg
			Supplier	Zinc (Zn)	7440-66-6		0.4511	mg
			Supplier	Iron (Fe)	7439-89-6		6.1254	mg
			Supplier	Copper (Cu)	7440-50-8		229.229	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3324	mg
Mold Compound-Black	151.67	mg		Epoxy Phenol Resin	proprietary data		21.2338	mg
			Supplier	Carbon Black (C)	1333-86-4		0.7583	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		128.9195	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.7583	mg
Plating	4.2	mg	В	Bismuth (Bi)	7440-69-9		0.0252	mg
			Supplier	Tin (Sn)	7440-31-5		4.1748	mg
Wire Bond - Au	1.52	mg	Supplier	Gold (Au)	7440-57-5		1.52	mg